

August 2015

## FCPF2250N80Z

# N-Channel SuperFET® II MOSFET

**800 V, 3.5 A, 2.25**  $\Omega$ 

### **Features**

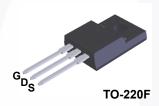
- $R_{DS(on)} = 1.8 \Omega (Typ.)$
- Ultra Low Gate Charge (Typ. Q<sub>q</sub> = 11 nC)
- Low E<sub>oss</sub> (Typ. 1.1 uJ @ 400V)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 51 pF)
- · 100% Avalanche Tested
- · RoHS Compliant
- · ESD Improved Capability

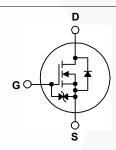
### **Applications**

- · AC DC Power Supply
- · LED Lighting

## **Description**

SuperFET<sup>®</sup> II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FCPF2250N80Z	Unit	
V <sub>DSS</sub>	Drain to Source Voltage			800	V	
\/	Cata to Source Valtage	- DC		±20	V	
$V_{GSS}$	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V	
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		3.5*	Α	
ID	Drain Current	- Continuous (T <sub>C</sub> = 100°C)		2.2*	A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	6.5*	Α	
E <sub>AS</sub>	Single Pulsed Avalanche Energ	у	(Note 2)	21.6	mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	0.52	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy		(Note 1)	0.22	mJ	
dv/dt	MOSFET dv/dt			100	V/ns	
αν/αι	Peak Diode Recovery dv/dt	Peak Diode Recovery dv/dt (Note 3)		20	V/IIS	
D	Dower Dissinction	(T <sub>C</sub> = 25°C)		21.9	W	
$P_{D}$	Power Dissipation - Derate Above 25°C		0.18	W/°C		
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperature for	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			οС	
Drain current limited	d by maximum junction temperature, with heat	sink.	"		1	

#### **Thermal Characteristics**

Symbol	Parameter	FCPF2250N80Z	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	5.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	10/00

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF2250N80Z	FCPF2250N80Z	TO-220F	Tube	N/A	N/A	50 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Parameter	Test Conditions	Min.	Тур.	Max.	Unit
cteristics					
Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	800	-	-	V
Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.85	-	V/°C
Zero Gate Voltage Drain Current	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	25	μΑ
	$V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	250	μΑ
Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±10	μΑ
	Cteristics  Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient  Zero Gate Voltage Drain Current				

#### **On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_{D} = 0.26$ mA	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 1.3 \text{ A}$	-	1.8	2.25	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 1.3 \text{ A}$	-	2.28	-	S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	1001/1/	-\	440	585	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	16	22	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	- 1 - 1 WILLS	-	0.75	-	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	8.4	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V	-	51	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 640 V, I <sub>D</sub> = 2.6 A,	-	11	14	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	2.2	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	4.3	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	2.8	-	Ω

### **Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time		-	11	32	ns
t <sub>r</sub>		$V_{DD} = 400 \text{ V}, I_D = 2.6 \text{ A},$	-	6.7	23	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$	- /	26	62	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	8.7	27	ns

#### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	3.5	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	6.5	Α
$V_{SD}$	Drain to Source Diode Forward Voltage V <sub>GS</sub>	<sub>S</sub> = 0 V, I <sub>SD</sub> = 2.6 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time V <sub>GS</sub>	<sub>S</sub> = 0 V, I <sub>SD</sub> = 2.6 A,	-	260	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge dI <sub>F</sub> /	/dt = 100 A/μs	-	2.2	-//	μС

#### Notes

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2.  $I_{AS}$  = 0.52 A,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C
- 3. I  $_{SD} \leq$  3.5 A, di/dt  $\leq$  200 A/µs, V  $_{DD} \leq$  BV  $_{DSS}$  , starting T  $_{J}$  = 25°C
- 4. Essentially independent of operating temperature typical characteristic.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

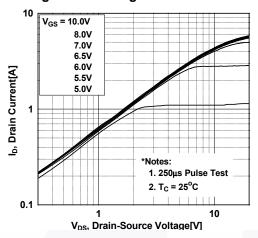


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

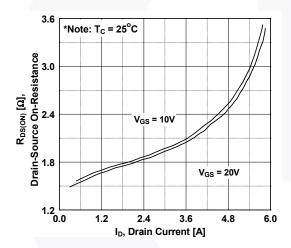


Figure 5. Capacitance Characteristics

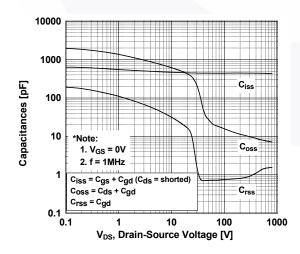


Figure 2. Transfer Characteristics

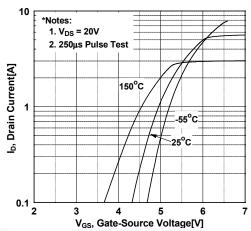


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

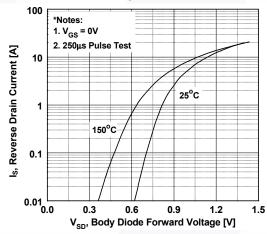
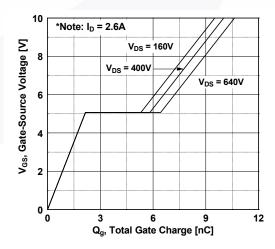


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

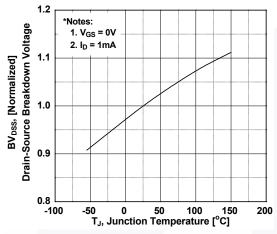


Figure 9. Maximum Safe Operating Area

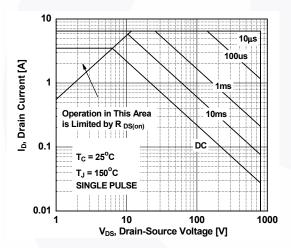


Figure 11. Eoss vs. Drain to Source Voltage

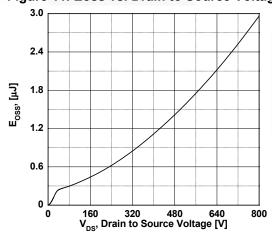


Figure 8. On-Resistance Variation vs. Temperature

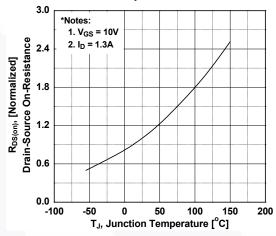
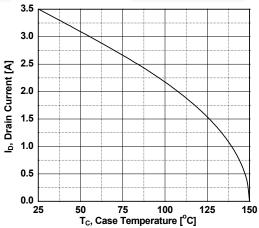
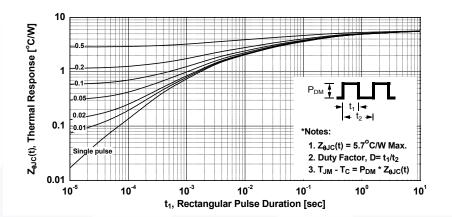


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics** (Continued)

Figure 12. Transient Thermal Response Curve



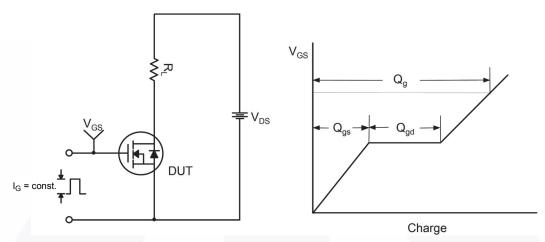


Figure 13. Gate Charge Test Circuit & Waveform

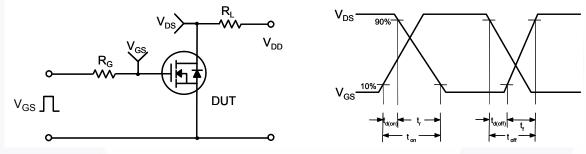


Figure 14. Resistive Switching Test Circuit & Waveforms

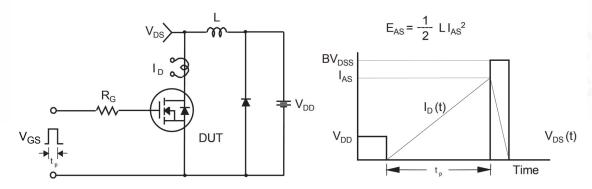


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

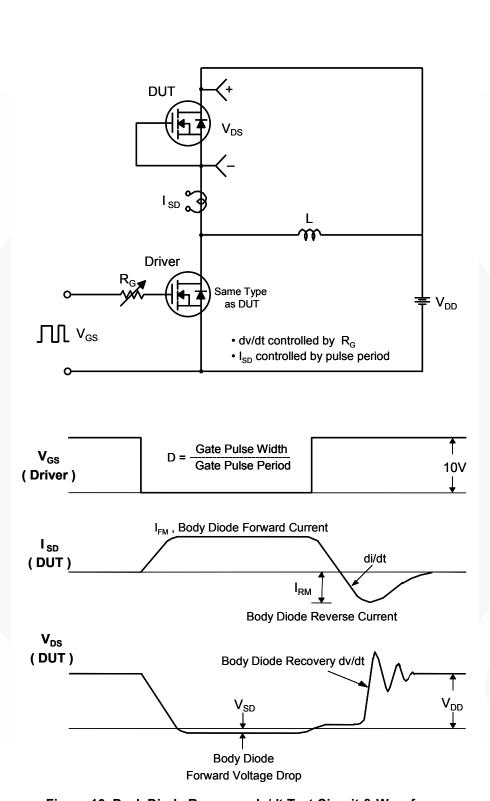
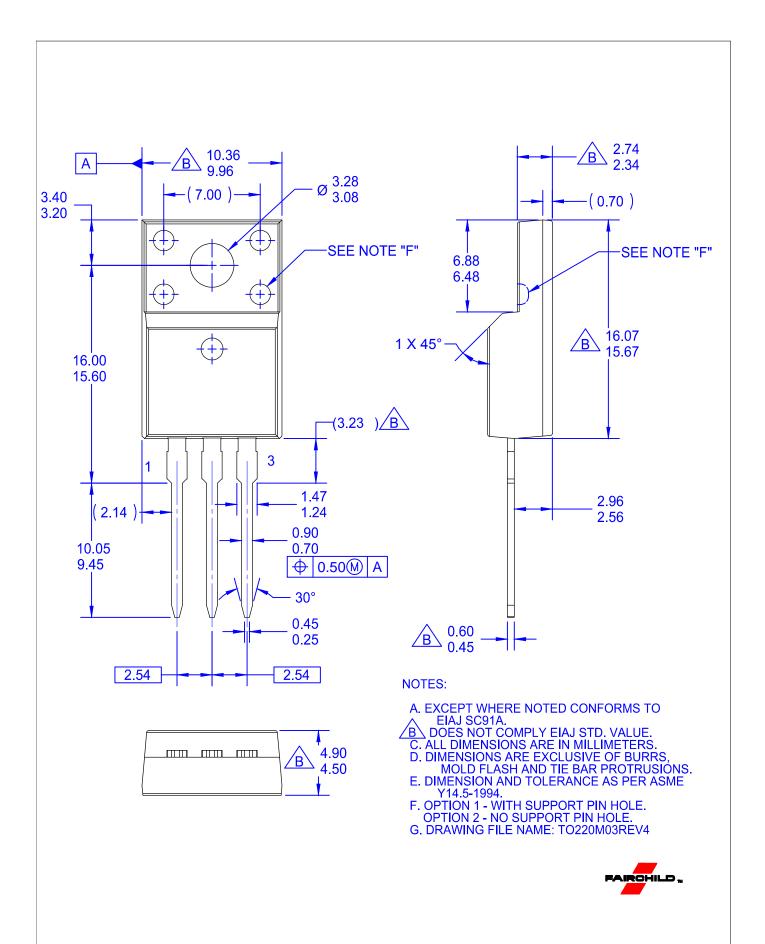


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and h

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative